

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jun-De Jin</td> <td>07/31/2012</td> </tr> <tr> <td>Ming Hsien Tsai</td> <td>07/31/2012</td> </tr> <tr> <td>Tzu-Jin Yeh</td> <td>07/31/2012</td> </tr> </tbody> </table>		Name	Execution Date	Jun-De Jin	07/31/2012	Ming Hsien Tsai	07/31/2012	Tzu-Jin Yeh	07/31/2012				
Name	Execution Date												
Jun-De Jin	07/31/2012												
Ming Hsien Tsai	07/31/2012												
Tzu-Jin Yeh	07/31/2012												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Hsin-Chu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Co., Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Hsin-Chu Science Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
Name:	Taiwan Semiconductor Manufacturing Co., Ltd.												
Street Address:	No. 8, Li-Hsin Rd. 6												
Internal Address:	Hsin-Chu Science Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13562571</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13562571								
Property Type	Number												
Application Number:	13562571												
CORRESPONDENCE DATA													
<p>Fax Number: 2165020601          Phone: 212-502-0600          Email: <a href="mailto:docketing@eschweilerlaw.com">docketing@eschweilerlaw.com</a>  <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>          Correspondent Name: Eschweiler &amp; Associates, LLC.          Address Line 1: 629 Euclid Avenue, Suite 1000          Address Line 2: National City Bank Building          Address Line 4: Cleveland, OHIO 44114</p>													
ATTORNEY DOCKET NUMBER:	TSMCP184US												
NAME OF SUBMITTER:	Thomas G. Eschweiler												

OP \$40.00 13562571

Total Attachments: 5

source=Assignment#page1.tif

source=Assignment#page2.tif

source=Assignment#page3.tif

source=Assignment#page4.tif

source=Assignment#page5.tif

**PATENT**

**REEL: 028684 FRAME: 0859**

U.S. Patent Appln. No.

Docket No. TSMCP184US

Filing Date:

**PATENT ASSIGNMENT**

**PARTIES TO THE ASSIGNMENT**

Assignor(s):

Jun-De Jin  
Rm. 3, 11F, No.645, Section 2, Kuang-Fu Rd., East Dist.  
Hsinchu City  
Taiwan (R.O.C.)

Assignor(s):

Ming Hsien Tsai  
8F., No. 309, Siyuan Rd., Sindian City  
New Taipei City 231  
Taiwan (R.O.C.)

Assignor(s):

Tzu-Jin Yeh  
Room 23, 15F., No.247, Niupu E. Rd., Shiangshan District  
Hsinchu City 300  
Taiwan (R.O.C.)

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.  
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park  
Hsin-Chu, Taiwan 300-77  
Republic of China

**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled  
**"INTEGRATED PASSIVE DEVICE FILTER WITH FULLY ON-CHIP ESD  
PROTECTION"** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this  
Assignment on the same day as he/she signs the Declaration and Power of  
Attorney); or

☐ was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

U.S. Patent Appln. No.

Docket No. TSMCP184US

Filing Date:

☐ will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes and requests ASSIGNEE'S legal representatives, the attorneys associated with Customer No. \_\_\_\_\_, to insert below in this document this APPLICATION's U.S. Serial Number and filing date, when known:

U.S. Serial No. \_\_\_\_\_,

filed on \_\_\_\_\_.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all

U.S. Patent Appln. No.

Docket No. TSMCP184US

Filing Date:

letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2012/07/31

Date

Jun-De JinName 1<sup>st</sup> Inventor Jun-De Jin

U.S. Patent Appln. No.

Docket No. TSMCP184US

Filing Date:

2012/07/31

Date

Ming-Hsien Tsai

Name 2<sup>nd</sup> Inventor Ming Hsien Tsai

U.S. Patent Appln. No.

Docket No. TSMCP184US

Filing Date:

2012/07/31

Date

Tzu-Jin Yeh

Name 3<sup>rd</sup> Inventor Tzu-Jin Yeh